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## ABSTRACT

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An electronic package comprises a first die having at least one first interconnect with solder over or under a first metal feature. A second die has at least one second interconnect to the first die, each second interconnect comprising a second metal feature comprising copper, solder over or under the second metal feature, and a layer between the solder and the second metal feature, wherein the layer comprises iron and has a different material than material of the first interconnect.

